



## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752</b> Distribute	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2014-09-05</b>
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giuseppe Vitali Palma	<b>Representative Title</b>	AMS/IPD Materials Declaration Champion)
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	PZ07*LB05FC2	A	SH1A	2014-09-05
Amount	UoM	Unit type	ST ECOPACK Grade	
76.29	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used okel/Palladium/Silver/Gold (Ni/Pd/Ag/		Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85X3.9X1.52	3	gull wing	
Comment	Package: SO 08 .15 JEDEC; MD valid for L79L05ACD13TR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	PZ07*LB05FC2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	0.903	mg	supplier	die	Silicon (Si)	7440-21-3		0.883	mg	977852	11574
				supplier	metallization	Aluminium (Al)	7429-90-5		0.011	mg	12182	144
				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.004	mg	4430	52
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.005	mg	5537	66
Leadframe	Copper & its alloys	33.558	mg	supplier	alloy	Copper (Cu)	7440-50-8		33.468	mg	997318	438694
				supplier	alloy	Iron (Fe)	7439-89-6		0.015	mg	447	197
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.028	mg	834	367
				supplier	metallization	Nickel (Ni)	7440-02-0		0.044	mg	1311	577
				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	30	13
				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	30	13
				supplier	metallization	Silver (Ag)	7440-22-4		0.001	mg	30	13
Die attach	Other Organic Materials	0.381	mg	supplier	glue	Silver (Ag)	7440-22-4		0.347	mg	910761	4548
				supplier	glue	acrylate	Proprietary		0.019	mg	49869	249
				supplier	glue	Methacrylate	Proprietary		0.015	mg	39370	197
Bonding wire	Other inorganic materials	0.02	mg	supplier	wire	Copper (Cu)	7440-50-8		0.02	mg	1000000	262
encapsulation	Other Organic Materials	41.428	mg	supplier	mold compound	Epoxy Resin	Proprietary		3.107	mg	74998	40726
				supplier	mold compound	Phenol Resin	Proprietary		2.071	mg	49990	27146
				supplier	mold compound	Silica, vitreous	60676-86-0		35.877	mg	866008	470271
				supplier	mold compound	Carbon black	1333-86-4		0.207	mg	4997	2713
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.166	mg	4007	2176